

Chip Scale Review

2015 Editorial Calendar

January • February

Semiconductor industry market update	<ul style="list-style-type: none"> • SEMI European 3D TSV Summit Grenoble, France (Jan 19-21) • APEX Expo San Diego, CA (February 24-26) • BiTS Workshop Mesa, AZ (March 15-18) • IMAPS Device Packaging (DPC) Fountain Hills, AZ (March 16-19) • SEMICON China Shanghai China (March 17-19) • Productronica China Shanghai China (March 17-19)
Next generation device packaging	
3D TSVs	
Bonding challenges for 3D ICs	
3D topography inspection for HVM	
Solid state laser ablation	
Wafer probing	
Advances in test and burn-in sockets	

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 16 - Ad Materials Deadline Jan 23

March • April

Future of mobile packaging & integration challenges	<ul style="list-style-type: none"> • SEMICON South East Asia Penang, Malaysia (Apr 22-24)
RF probe technologies	
Electronic packaging materials	
FOWLP technology	
Flip-chip packaging	
3D MEMS WLP	
Inspection and metrology for advanced wafer packaging	
OSATS update	

International Directory of IC Packaging Foundries

Ad Space Close Feb 27 - Materials Close Mar 6

May • June

Advanced 3D integration challenges	<ul style="list-style-type: none"> • MEPTEC MEMS Technology San Jose, CA (May 20) • IoT Symposium San Jose, CA (May 21) • ECTC San Diego, CA (May 26-29) • IMAPS Advanced Technology Workshop Dearborn, MI (June 3-4) • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 7-10) • SEMI Europe Packaging Tech Seminar Porto, Portugal (June 18) • SEMICON West San Francisco, CA (July 14-16)
Thermal management of ICs	
Interposer reliability	
Wafer-level CSPs	
Thin wafer-handling	
MEMS Standards and Roadmap	
Dispensing technologies	
Reducing the cost-of-test	
Burn-in & test of packaged ICs*	
Inline monitoring of advanced packaging processes	

*Awarded to best paper from BiTS Workshop 2015

Ad Space Close April 4 - Ad Materials Close April 10

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July • August

Plasma cleaning technologies	<ul style="list-style-type: none"> • SEMICON Taiwan Taipei, Taiwan (Sept 2-4) • MEPTEC Medical Microelectronics Conference Portland, OR (Sept 16-17) • SEMI European MEMS Summit Milan, Italy (Sept 17-18)
Failure analysis	
Collaboration in materials and processing technology	
Metrology & defect inspection	
Discrete power devices	
Cu pillar bumping	
MEMS IoT	
Solder reliability	

Ad Space Close Jun 6 - Ad Materials Close Jun 12

September • October

System scaling for smart mobile systems	<ul style="list-style-type: none"> • SEMICON Europa Dresden, Germany (Oct 6-8) • International Test Conference (ITC) Anaheim, CA (Oct 6 - 8) • IWLPC-International Wafer-Level Packaging Conference & Exhibition San Jose, CA (Oct 13 -15) • IMAPS 2015 Orlando, FL (Oct 26-29) • Productronica Munich, Germany (Nov 10-13) • MEMS Executive Congress Napa, CA (TBD)
Interposers	
Next generation SiP	
Wafer-level packaging processes and performance	
Test trends	
Fan out wafer level packaging	
Wirebonding	
Design-for-test for stacked ICs	
Packaging, assembly and test in Europe	

Ad Space Close Aug 15 - Ad Materials Close Aug 21

November • December

Recent advances in 3D package reliability	<ul style="list-style-type: none"> • RTI 3D ASIP Conference Burlingame, CA (Dec 9-11) • SEMICON Japan Tokyo, Japan (Dec 16-18) • SEMI European 3D TSV Summit 2016 Grenoble, France (Jan 18-20)
Die stacking	
Heterogeneous integration	
Future of packaging	
3D IC standards update	
Underfill, encapsulants, and adhesives	
PoP	
MEMS automotive applications	

Ad Space Close Oct 10 - Materials Close Oct 16

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